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The term "paste" used in the present invention means a paste, e.g., an adhesive and paint, which has such a level of viscosity as allowing the liquid material to be laid on the paste-applied surface in the linear form. One example of the liquid material is a thermosetting conductive resin.

Please replace the paragraph beginning at page 2, line 11 with the following rewritten paragraph:

A³
An object of the present invention is to provide a paste pad forming method which can apply a paste, with much less variations in liquid amount than resulted by the prior-art method of arranging a number of nozzles in a desired drawing pattern for multi-dot coating, and which can completely prevent a bubble from being entrapped in a step of bonding a bonded member, e.g., a semiconductor chip, to a paste-applied body, e.g., a lead frame, through the applied paste.